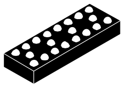
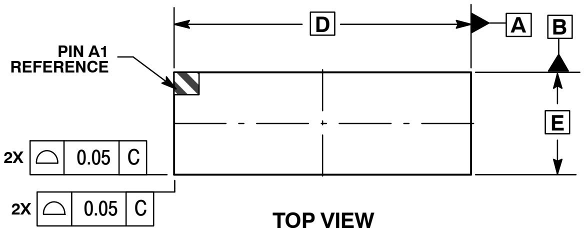
WLCSP20, 3.27x1.13
CASE 567BW
ISSUE O

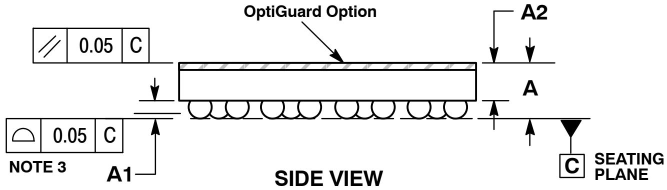


SCALE 4:1

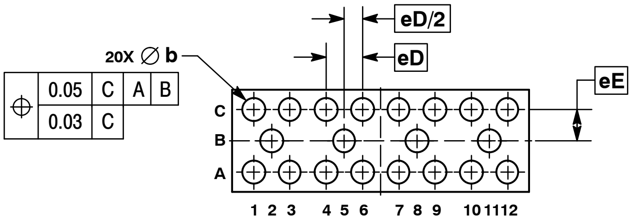
DATE 26 JUL 2010



TOP VIEW

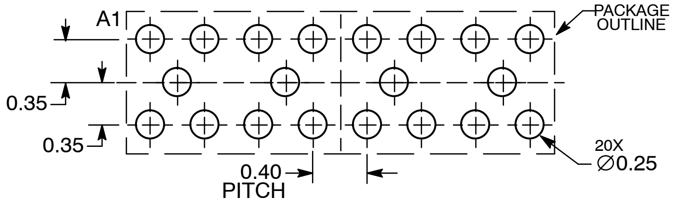


SIDE VIEW



BOTTOM VIEW

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS	
DIM	**MIN**	**MAX**
A	0.54	0.69
A1	0.17	0.24
A2	0.42 REF	
b	0.24	0.29
D	3.27 BSC	
E	1.13 BSC	
eD	0.400 BSC	
eE	0.347 BSC	

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DESCRIPTION:	**WLCSP20, 3.27x1.13**	**PAGE 1 OF 1**